

ABSTRACT OF THE DISCLOSURE

A polishing slurry for CMP of Cu, which comprises
a first complexing agent containing a heterocyclic
compound which is capable of forming a water-insoluble
5 complex with Cu, and a second complexing agent
containing a heterocyclic compound which is capable of
forming a slightly water-soluble or water-soluble
complex with Cu to thereby provide at least one extra
ligand subsequent to formation of the complex.